

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	4 X 4 X 0.75 (2.5 EP)
Lead Count	24
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	3.35E-02	86.91	869100	45.31		453115
Thermosets	Epoxy & Phenol Resin	Proprietary	4.92E-03	12.78	127800	6.66		66630
Other inorganic materials	Carbon black	1333-86-4	1.19E-04	0.31	3100	0.16		1616
Subtotal			3.85E-02	100.00	1000000	52.14		521361

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	2.84 E-02	97.5	975000	38.39		383928
Copper & its alloys	Iron	7439-89-6	6.84 E-04	2.35	23500	0.93		9254
Copper & its alloys	Zinc	7440-66-6	3.49 E-05	0.12	1200	0.05		473
Copper & its alloys	Phosphorus	7723-14-0	8.73 E-06	0.03	300	0.01		118
Subtotal			2.91 E-02	100.00	1000000	39.38		393772

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.18 E-03	100.0	1000000	1.60		15981

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	1.96 E-03	100.0	1000000	2.65		26461

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	1.34 E-04	99.0	990000	0.18		1816
Precious metals	Palladium	7440-05-3	1.36 E-06	1.0	10000	0.00		18
Subtotal			1.36 E-04	100.0	1000000	0.18		1834

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	2.30 E-03	100.0	1000000	3.12		31177

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	5.42 E-04	77.71	777100	0.73		7329
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	2.17 E-05	3.11	31100	0.03		293
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	2.17 E-05	3.11	31100	0.03		293
Other organic materials	Butyrolactone, gamma-	96-48-0	2.17 E-05	3.11	31100	0.03		293
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	2.17 E-05	3.11	31100	0.03		293
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	2.17 E-05	3.11	31100	0.03		293
Other organic materials	Organosilane	TS ref# 10001	2.17 E-05	3.11	31100	0.03		293
Other inorganic materials	Copper(II) oxide	1317-38-0	2.17 E-05	3.11	31100	0.03		293
Other organic materials	Epoxy resin modifier	TS ref# 10038	3.62 E-06	0.52	5200	0.005		49
Subtotal			6.97 E-04	100.0	1000000	0.94		9432

Package Totals			Weight (g)	7.39 E-02		Percentage (%)	100	PPM	1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	4 X 4 X 0.75 (2.5 EP)
Lead Count	24
Terminal Finish	NiPdAu

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.48E-02	83.25	832500	47.09	470913
Thermosets	Epoxy resin	Proprietary	2.27E-03	5.42	54200	3.07	30659
Thermosets	Phenol resin	Proprietary	1.44E-03	3.45	34500	1.95	19515
Other inorganic materials	Metal Hydroxide	Proprietary	2.27E-03	5.42	54200	3.07	30659
Others	Others	Proprietary	1.03E-03	2.46	24600	1.39	13915
Subtotal			4.18E-02	100.00	1000000	56.57	565661

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.87 E-02	97.50	975000	38.89	388942
Copper & its alloys	Iron	7439-89-6	6.93 E-04	2.35	23500	0.94	9375
Copper & its alloys	Zinc	7440-66-6	3.54 E-05	0.12	1200	0.05	479
Copper & its alloys	Phosphorus	7723-14-0	8.84 E-06	0.03	300	0.01	120
Subtotal			2.95 E-02	100.00	1000000	39.89	398915

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	7.11 E-04	97.3	973000	0.96	9626
Precious metals	Palladium	7440-05-3	1.61 E-05	2.2	22000	0.02	218
Precious metals	Gold	7440-57-5	3.66 E-06	0.5	5000	0.00	49
Subtotal			7.31 E-04	100.00	1000000	0.99	9893

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.57 E-04	100.0	1000000	0.21	2128

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.30 E-03	100.0	1000000	1.76	17552

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.33 E-04	77.00	770000	0.45	4505
Other organic materials	Acrylic resin	Proprietary	3.03 E-05	7.00	70000	0.04	410
Other organic materials	Acrylate	Proprietary	2.38 E-05	5.50	55000	0.03	322
Other organic materials	Polybutadiene derivative	Proprietary	1.95 E-05	4.50	45000	0.03	263
Thermoset	Epoxy resin	Proprietary	1.08 E-05	2.50	25000	0.01	146
Other organic materials	Butadiene Copolymer	Proprietary	6.49 E-06	1.50	15000	0.009	88
Others	Additive	Proprietary	6.49 E-06	1.50	15000	0.009	88
Others	Peroxide	Proprietary	2.16 E-06	0.50	5000	0.003	29
Subtotal			4.32 E-04	100.0	1000000	0.59	5851

Package Totals	Weight (g)	Percentage (%)	PPM
	7.39 E-02	100.00	1000000

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